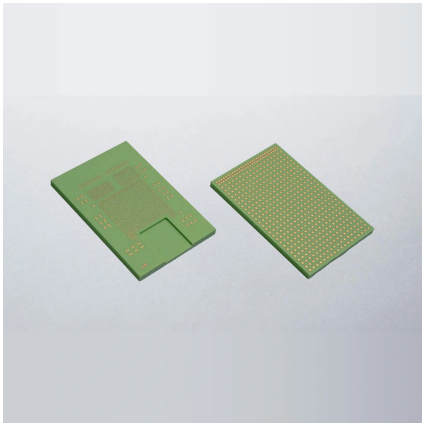

LTCC glass-ceramic multilayer substrates with metallized pads

LTCC Glass-Ceramic Multilayer Substrates

Product ID / SKU: FWM/CS-ALU-014

Material: LTCC Glass-Ceramic

Product type: Ceramic Substrate

Low-temperature co-fired glass-ceramic multilayer substrates for high-frequency and compact electronic packaging; this route is related to, but not classified as, 96% or 99.6% dense alumina.

LTCC Glass-Ceramic (GL570) Properties

Material property	GL570 - LTCC glass-ceramic	Test condition / basis
Relative permittivity	5.6 / 5.7	1 MHz / 2 GHz, respectively
Dielectric loss tangent	0.0003 / 0.0007	1 MHz / 2 GHz, respectively
Thermal conductivity	2.8 W/(m·K)	-
Coefficient of thermal expansion	3.4×10^{-6}/K	Room temperature-400°C
Bending strength	200 MPa	Three-point bending
Co-fire-compatible conductor	Copper	Co-fired material system